

Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	RXv2
Core Size	32-Bit Single-Core
Speed	54MHz
Connectivity	I ² C, IrDA, SCI, SD/SDIO, SPI, SSI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	30
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LFQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f52315cdfl-30

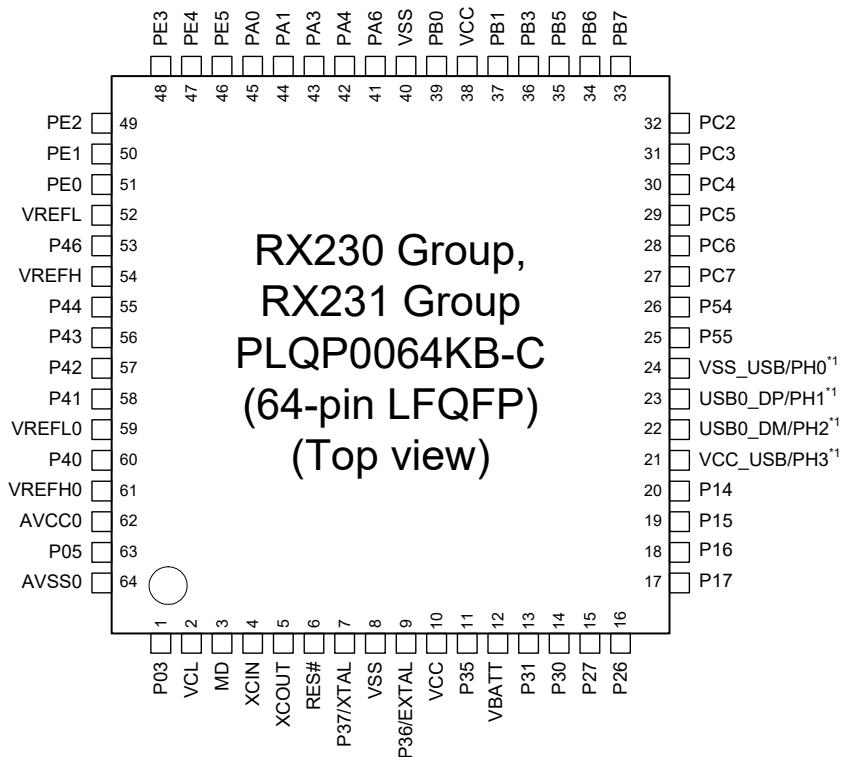
Table 1.1 Outline of Specifications (3/4)

Classification	Module/Function	Description
Timers	Independent watchdog timer (IWDTa)	<ul style="list-style-type: none"> • 14 bits × 1 channel • Count clock: Dedicated low-speed on-chip oscillator for the IWDT • Frequency divided by 1, 16, 32, 64, 128, or 256
	Realtime clock (RTCe)	<ul style="list-style-type: none"> • Clock source: Sub-clock • Time/calendar • Interrupts: Alarm interrupt, periodic interrupt, and carry interrupt • Time-capture facility for three values
	Low power timer (LPT)	<ul style="list-style-type: none"> • 16 bits × 1 channel • Clock source: Sub-clock, Dedicated low-speed on-chip oscillator for the IWDT • Frequency divided by 2, 4, 8, 16, or 32
	8-bit timer (TMR)	<ul style="list-style-type: none"> • (8 bits × 2 channels) × 2 units • Seven internal clocks (PCLK/1, PCLK/2, PCLK/8, PCLK/32, PCLK/64, PCLK/1024, and PCLK/8192) and an external clock can be selected • Pulse output and PWM output with any duty cycle are available • Two channels can be cascaded and used as a 16-bit timer
Communication functions	Serial communications interfaces (SCIg, SC Ih)	<ul style="list-style-type: none"> • 7 channels (channel 0, 1, 5, 6, 8, 9: SCIg, channel 12: SC Ih) • SCIg <ul style="list-style-type: none"> • Serial communications modes: Asynchronous, clock synchronous, and smart-card interface • Multi-processor function • On-chip baud rate generator allows selection of the desired bit rate • Choice of LSB-first or MSB-first transfer • Average transfer rate clock can be input from TMR timers for SCI5, SCI6, and SCI12 • Start-bit detection: Level or edge detection is selectable. • Simple I²C • Simple SPI • 9-bit transfer mode • Bit rate modulation • Event linking by the ELC (only on channel 5) • SC Ih (The following functions are added to SCIg) <ul style="list-style-type: none"> • Supports the serial communications protocol, which contains the start frame and information frame • Supports the LIN format
	IrDA interface (IRDA)	<ul style="list-style-type: none"> • 1 channel (SCI5 used) • Supports encoding/decoding of waveforms conforming to IrDA standard 1.0
	I²C bus interface (RIICa)	<ul style="list-style-type: none"> • 1 channel • Communications formats: I²C bus format/SMBus format • Master mode or slave mode selectable • Supports fast mode
	Serial peripheral interface (RSPPIa)	<ul style="list-style-type: none"> • 1 channel • Transfer facility <ul style="list-style-type: none"> • Using the MOSI (master out, slave in), MISO (master in, slave out), SSL (slave select), and RSPCK (RSPPI clock) enables serial transfer through SPI operation (four lines) or clock-synchronous operation (three lines) • Capable of handling serial transfer as a master or slave • Data formats • Choice of LSB-first or MSB-first transfer <ul style="list-style-type: none"> • The number of bits in each transfer can be changed to 8, 9, 10, 11, 12, 13, 14, 15, 16, 20, 24, or 32 bits. • 128-bit buffers for transmission and reception • Up to four frames can be transmitted or received in a single transfer operation (with each frame having up to 32 bits) • Double buffers for both transmission and reception
	USB 2.0 host/function module (USBd)	<ul style="list-style-type: none"> • USB Device Controller (UDC) and transceiver for USB 2.0 are incorporated. • Host/function module: 1 port • Compliant with USB version 2.0 • Transfer speed: Full-speed (12 Mbps), low-speed (1.5 Mbps) • OTG (ON-The-Go) is supported. • Isochronous transfer is supported. • BC1.2 (Battery Charging Specification Revision 1.2) is supported. • Internal power supply for USB (allows operation without external power input to the VCC_USB pin when VCC = 4.0 to 5.5V)
	CAN module (RSCAN)	<ul style="list-style-type: none"> • 1 channel • Compliance with the ISO11898-1 specification (standard frame and extended frame) • 16 Message boxes

Table 1.2 Comparison of Functions for Different Packages

Module/Functions		RX230 Group			RX231 Group		
		100 Pins	64 Pins	48 Pins	100 Pins	64 Pins	48 Pins
External bus	External bus	16 bit	Not supported		16 bit	Not supported	
Interrupts	External interrupts	NMI, IRQ0 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7	NMI, IRQ0 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7
DMA	DMA controller	4 channels (DMAC0 to DMAC3)			4 channels (DMAC0 to DMAC3)		
	Data transfer controller	Available			Available		
Timers	16-bit timer pulse unit	6 channels (TPU0 to TPU5)			6 channels (TPU0 to TPU5)		
	Multi-function timer pulse unit 2	6 channels (MTU0 to MTU5)			6 channels (MTU0 to MTU5)		
	Port output enable 2	POE0# to POE3#, POE8#			POE0# to POE3#, POE8#		
	8-bit timer	2 channels× 2 units			2 channels× 2 units		
	Compare match timer	2 channels× 2 units			2 channels× 2 units		
	Low power timer	1 channel			1 channel		
	Realtime clock	Available		Not supported	Available		Not supported
	Watchdog timer	Available			Available		
Communication functions	Independent watchdog timer	Available			Available		
	Serial communications interfaces (SCIg)	6 channels (SCI0, 1, 5, 6, 8, 9)	5 channels (SCI1, 5, 6, 8, 9)	4 channels (SCI1, 5, 6, 8)	6 channels (SCI0, 1, 5, 6, 8, 9)	5 channels (SCI1, 5, 6, 8, 9)	4 channels (SCI1, 5, 6, 8)
	IrDA interface	1 channel (SCI5)			1 channel (SCI5)		
	Serial communications interfaces (SCIh)	1 channel (SCI12)			1 channel (SCI12)		
	I ² C bus interface	1 channel			1 channel		
	CAN module	Not supported			1 channel*1		
	Serial peripheral interface	1 channel			1 channel		
	USB 2.0 host/function module	Not supported			1 channel		
	Serial sound interface	1 channel			1 channel		
	SD Host Interface	Not supported			1 channel*1		Not supported
	Capacitive touch sensing unit	24 channels	10 channels	6 channels	24 channels	10 channels	6 channels
	12-bit A/D converter (including high-precision channels)	24 channels (8 channels)	12 channels (6 channels)	8 channels (4 channels)	24 channels (8 channels)	12 channels (6 channels)	8 channels (4 channels)
	Temperature sensor	Available			Available		
	D/A converter	2 channels		Not supported	2 channels		Not supported
	CRC calculator	Available			Available		
	Event link controller	Available			Available		
	Comparator B	4 channels			4 channels		
	Packages	100-pin TFLGA 100-pin LFQFP	64-pin WFLGA 64-pin HWQFN 64-pin LFQFP	48-pin HWQFN 48-pin LFQFP	100-pin TFLGA 100-pin LFQFP	64-pin WFLGA 64-pin HWQFN 64-pin LFQFP	48-pin HWQFN 48-pin LFQFP

Note 1. Only for chip version B



- Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table "List of Pins and Pin Functions (64-Pin LFQFP/HWQFN)".
- Note 1. RX230: PH0, PH1, PH2, PH3
RX231: VSS_USB, USB0_DP, USB0_DM, VCC_USB

Figure 1.7 Pin Assignments of the 64-Pin LFQFP

Table 1.6 List of Pins and Pin Functions (100-Pin TFLGA) (2/3)

Pin No.	Power Supply, Clock, System Control	I/O Port	External Bus	Timers (MTU, TPU, TMR, RTC, CMT, POE, CAC)	Communications (SCI, RSPI, RIIC, RSCAN, USB, SSI)	Memory Interface (SDHI)	Touch sensing	Others
E8		PA4	A4	MTIC5U/MTCLKA/TMRI0/TIOCA1	TXD5/SMOSI5/SSDA5/SSLA0/SSITXD0/IRTXD5			IRQ5 / CVREFB1
E9		PA5	A5	TIOCB1	RSPCKA			
E10		PA3	A3	MTIOC0D/MTCLKD/TIOCD0/TCLKB	RXD5/SMISO5/SSCL5/SSIRXD0/IRRXD5			IRQ6 / CMPB1
F1	EXTAL	P36						
F2	VCC							
F3	UPSEL	P35						NMI
F4		P32		MTIOC0C/TMO3/TIOCC0/RTCOOUT/RTCIC2	TXD6/SMOSI6/SSDA6/USB0_VBUSEN			IRQ2
F5		P12		TMCI1	SCL			IRQ2
F6		PB3	A11	MTIOC0A/MTIOC4A/TMO0/POE3#/TIOCD3/TCLKD	SCK6	SDHI_W_P		
F7		PB2	A10	TIOCC3/TCLKC	CTS6#/RTS6#/SS6#			
F8		PB0	A8	MTIC5W/TIOCA3	RXD6/SMISO6/SSCL6/RSPCKA	SDHI_C_MD		
F9		PA7	A7	TIOCB2	MISOA			
F10	VSS							
G1		P33		MTIOC0D/TMRI3/POE3#/TIOCD0	RXD6/SMISO6/SSCL6		TS1	IRQ3
G2		P31		MTIOC4D/TMCI2/RTCIC1	CTS1#/RTS1#/SS1#/SSISCK0			IRQ1
G3		P30		MTIOC4B/TMRI3/POE8#/RTCIC0	RXD1/SMISO1/SSCL1/AUDIO_MCLK			IRQ0/CMPOB3
G4		P27	CS3#	MTIOC2B/TMCI3	SCK1/SSIWS0		TS2	CVREFB3
G5	BCLK	P53					TS17	
G6		P52	RD#				TS18	
G7		PB5	A13	MTIOC2A/MTIOC1B/TMR11/POE1#/TIOCB4	SCK9/USB0_VBUS	SDHI_CD		
G8		PB4	A12	TIOCA4	CTS9#/RTS9#/SS9#			
G9		PB1	A9	MTIOC0C/MTIOC4C/TMCI0/TIOCB3	TXD6/SMOSI6/SSDA6	SDHI_CL_K		IRQ4/CMPOB1
G10	VCC							
H1		P26	CS2#	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1/SSIRXD0		TS3	CMPB3
H2		P25	CS1#	MTIOC4C/MTCLKB/TIOCA4			TS4	ADTRG0#
H3		P16		MTIOC3C/MTIOC3D/TMO2/TIOCB1/TCLKC/RTCOOUT	TXD1/SMOSI1/SSDA1/MOSIA/SCL/USB0_VBUS/USB0_VBUSEN/USB0_OVRCURB			IRQ6/ADTRG0#
H4		P15		MTIOC0B/MTCLKB/TMCI2/TIOCB2/TCLKB	RXD1/SMISO1/SSCL1/CRXD0		TS12	IRQ5/CMPB2
H5		P55	WAIT#	MTIOC4D/TMO3	CRXD0		TS15	
H6		P54	ALE	MTIOC4B/TMCI1	CTXD0		TS16	
H7	UB	PC7	A23/CS0#	MTIOC3A/MTCLKB/TMO2	TXD8/SMOSI8/SSDA8/MISOA			CACREF
H8		PC6	A22/CS1#	MTIOC3C/MTCLKA/TMCI2	RXD8/SMISO8/SSCL8/MOSIA		TS22	
H9		PB6	A14	MTIOC3D/TIOCA5	RXD9/SMISO9/SSCL9	SDHI_D1		
H10		PB7	A15	MTIOC3B/TIOCB5	TXD9/SMOSI9/SSDA9	SDHI_D2		
J1		P24	CS0#	MTIOC4A/MTCLKA/TMRI1/TIOCB4	USB0_VBUSEN		TS5	
J2		P21		MTIOC1B/TMCI0/TIOCA3	RXD0/SMISO0/SSCL0/USB0_EXICEN/SSIWS0		TS8	
J3		P17		MTIOC3A/MTIOC3B/TMO1/POE8#/TIOCB0/TCLKD	SCK1/MISOA/SDA/SSITXD0			IRQ7/CMPOB2
J4		P13		MTIOC0B/TMO3/TIOCA5	SDA			IRQ3
J5	VSS_USB*1	PH0*1						CACREF*1

4. I/O Registers

This section provides information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to registers are also given below.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

When writing to an I/O register, the CPU starts executing the subsequent instruction before completing I/O register write. This may cause the subsequent instruction to be executed before the post-update I/O register value is reflected on the operation.

As described in the following examples, special care is required for the cases in which the subsequent instruction must be executed after the post-update I/O register value is actually reflected.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERn of the ICU (interrupt request enable bit) cleared to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

- Write to an I/O register.
- Read the value from the I/O register to a general register.
- Execute the operation using the value read.
- Execute the subsequent instruction.

[Instruction examples]

- Byte-size I/O registers

```
MOV.L #SFR_ADDR, R1  
MOV.B #SFR_DATA, [R1]  
CMP [R1].UB, R1  
;; Next process
```

- Word-size I/O registers

```
MOV.L #SFR_ADDR, R1  
MOV.W #SFR_DATA, [R1]  
CMP [R1].W, R1  
;; Next process
```


Table 4.1 List of I/O Registers (Address Order) (21/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK < PCLK
000A 0008h	USB0	Device State Control Register 0	DVSTCTRL0	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0014h	USB0	CFIFO Port Register	CFIFO	16	16	3, 4 PCLKB	2 ICLK
000A 0018h	USB0	D0FIFO Port Register	D0FIFO	16	16	3, 4 PCLKB	2 ICLK
000A 001Ch	USB0	D1FIFO Port Register	D1FIFO	16	16	3, 4 PCLKB	2 ICLK
000A 0020h	USB0	CFIFO Port Select Register	CFIFOSEL	16	16	3, 4 PCLKB	2 ICLK
000A 0022h	USB0	CFIFO Port Control Register	CFIFOCTR	16	16	3, 4 PCLKB	2 ICLK
000A 0028h	USB0	D0FIFO Port Select Register	D0FIFOSEL	16	16	3, 4 PCLKB	2 ICLK
000A 002Ah	USB0	D0FIFO Port Control Register	D0FIFOCTR	16	16	3, 4 PCLKB	2 ICLK
000A 002Ch	USB0	D1FIFO Port Select Register	D1FIFOSEL	16	16	3, 4 PCLKB	2 ICLK
000A 002Eh	USB0	D1FIFO Port Control Register	D1FIFOCTR	16	16	3, 4 PCLKB	2 ICLK
000A 0030h	USB0	Interrupt Enable Register 0	INTENB0	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0032h	USB0	Interrupt Enable Register 1	INTENB1	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0036h	USB0	BRDY Interrupt Enable Register	BRDYENB	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0038h	USB0	NRDY Interrupt Enable Register	NRDYENB	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 003Ah	USB0	BEMP Interrupt Enable Register	BEMPENB	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 003Ch	USB0	SOF Output Configuration Register	SOFCFG	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0040h	USB0	Interrupt Status Register 0	INTSTS0	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0042h	USB0	Interrupt Status Register 1	INTSTS1	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0046h	USB0	BRDY Interrupt Status Register	BRDYSTS	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0048h	USB0	NRDY Interrupt Status Register	NRDYSTS	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 004Ah	USB0	BEMP Interrupt Status Register	BEMPSTS	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 004Ch	USB0	Frame Number Register	FRMNUM	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0054h	USB0	USB Request Type Register	USBREQ	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0056h	USB0	USB Request Value Register	USBVAL	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 0058h	USB0	USB Request Index Register	USBINDX	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 005Ah	USB0	USB Request Length Register	USBLENG	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 005Ch	USB0	DCP Configuration Register	DCPCFG	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$
000A 005Eh	USB0	DCP Maximum Packet Size Register	DCPMAXP	16	16	9 PCLKB or more	Frequency with $1 + 9 \times (\text{frequency ratio of ICLK/PCLKB})^2$

Table 5.2 Recommended Operating Voltage Conditions

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Power supply voltages	VCC ^{*1, *2}	When USB is not used	1.8	—	5.5	V
		When USB is used When USB regulator is not used	3.0	—	3.6	
		When USB is used When USB regulator is used	4.0	—	5.5	
	VSS		—	0	—	
USB power supply voltages	VCC_USB	When USB regulator is not used	—	VCC	—	V
	VSS_USB		—	0	—	
VBATT power supply voltage	VBATT		1.8	—	5.5	V
Analog power supply voltages	AVCC0 ^{*1, *2}		1.8	—	5.5	V
			—	0	—	
			1.8	—	AVCC0	
			—	0	—	
			1.8	—	AVCC0	
			—	0	—	

Note 1. Use AVCC0 and VCC under the following conditions:

AVCC0 and VCC can be set individually within the operating range when $VCC \geq 2.0\text{ V}$

AVCC0 = VCC when $VCC < 2.0\text{ V}$

Note 2. When powering on the VCC and AVCC0 pins, power them on at the same time or the VCC pin first and then the AVCC0 pin.

5.2 DC Characteristics

Table 5.3 DC Characteristics (1)

Conditions: $2.7 \text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 5.5 \text{ V}$, $2.7 \text{ V} \leq \text{AVCC0} \leq 5.5 \text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0 \text{ V}$, $T_a = -40 \text{ to } +105^\circ\text{C}$

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Schmitt trigger input voltage	RIIC input pin (except for SMBus, 5 V tolerant)	V_{IH}	$\text{VCC} \times 0.7$	—	5.8	V		
	Ports 12, 13, 16, 17, port B5 (5 V tolerant)		$\text{VCC} \times 0.8$	—	5.8			
	Ports 14 to 15, ports 20 to 27, ports 33 to 37, ports 50 to 55, ports A0 to A7, ports B0 to B4, B6, B7, ports C0 to C7, ports D0 to D7, ports E0 to E7, port J3, Ports 30 to 32 (when time capture event input is not selected), RES#		$\text{VCC} \times 0.8$	—	$\text{VCC} + 0.3$			
	Ports 03, 05, 07, ports 40 to 47		$\text{AVCC0} \times 0.8$	—	$\text{AVCC0} + 0.3$			
	Ports 30 to 32 (when time capture event input is selected)		$\text{VCC} \times 0.8$	—	$\text{VCC} + 0.3$			
			$\text{VBATT} \times 0.8$	—	$\text{VBATT} + 0.3$			
	Ports 03, 05, 07, ports 40 to 47	V_{IL}	-0.3	—	$\text{AVCC0} \times 0.2$	V		
	RIIC input pin (except for SMBus)		-0.3	—	$\text{VCC} \times 0.3$			
	Other than RIIC input pin or ports 30 to 32		-0.3	—	$\text{VCC} \times 0.2$			
	Ports 30 to 32 (when time capture event input is selected)		-0.3	—	$\text{VCC} \times 0.3$			
			-0.3	—	$\text{VBATT} \times 0.3$			
	Ports 03, 05, 07, ports 40 to 47	ΔV_T	$\text{AVCC0} \times 0.1$	—	—			
	RIIC input pin (except for SMBus)		$\text{VCC} \times 0.05$	—	—			
	Ports 12, 13, 16, 17, Port B5		$\text{VCC} \times 0.05$	—	—			
	Other than RIIC input pin		$\text{VCC} \times 0.1$	—	—			
Input level voltage (except for Schmitt trigger input pins)	MD	V_{IH}	$\text{VCC} \times 0.9$	—	$\text{VCC} + 0.3$	V		
	EXTAL (external clock input)		$\text{VCC} \times 0.8$	—	$\text{VCC} + 0.3$			
	RIIC input pin (SMBus)		2.1	—	$\text{VCC} + 0.3$			
	MD	V_{IL}	-0.3	—	$\text{VCC} \times 0.1$			
	EXTAL (external clock input)		-0.3	—	$\text{VCC} \times 0.2$			
	RIIC input pin (SMBus)		-0.3	—	0.8			

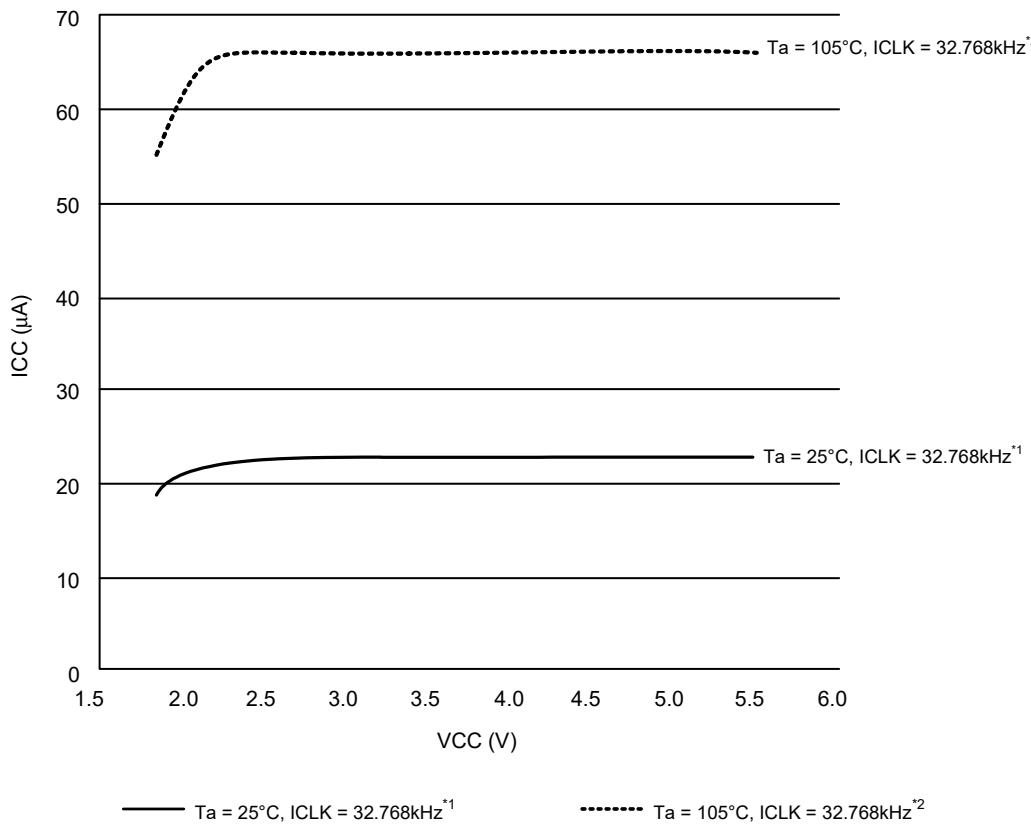


Figure 5.3 Voltage Dependency in Low-Speed Operating Mode (Reference Data)

Table 5.8 DC Characteristics (6)Conditions: $1.8 \text{ V} \leq \text{VCC} = \text{VCC_USB} = \text{AVCC0} \leq 5.5 \text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0 \text{ V}$, $T_a = -40 \text{ to } +105^\circ\text{C}$

Item		Symbol	Typ.* ³	Max.	Unit	Test Conditions
Supply current ^{*1}	Software standby mode ^{*2}	I_{CC}	0.8	3.7	μA	
			1.2	4.3		
			3.5	18.6		
			7.9	45.2		
	Increment for IWDT operation		0.4	—		Use IWDT-Dedicated On-Chip Oscillator for clock source
			0.4	—		
	Increment for LPT operation		0.4	—		RCR3.RTCVD[2:0] set to low drive capacity
			0.4	—		
	Increment for RTC operation ^{*4}		1.2	—		RCR3.RTCVD[2:0] set to normal drive capacity

Note 1. Supply current values are with all output pins unloaded and all input pull-up MOSs in the off state.

Note 2. The IWDT, LVD, and CMPB are stopped.

Note 3. When VCC is 3.3 V.

Note 4. This increment includes the oscillation circuit.

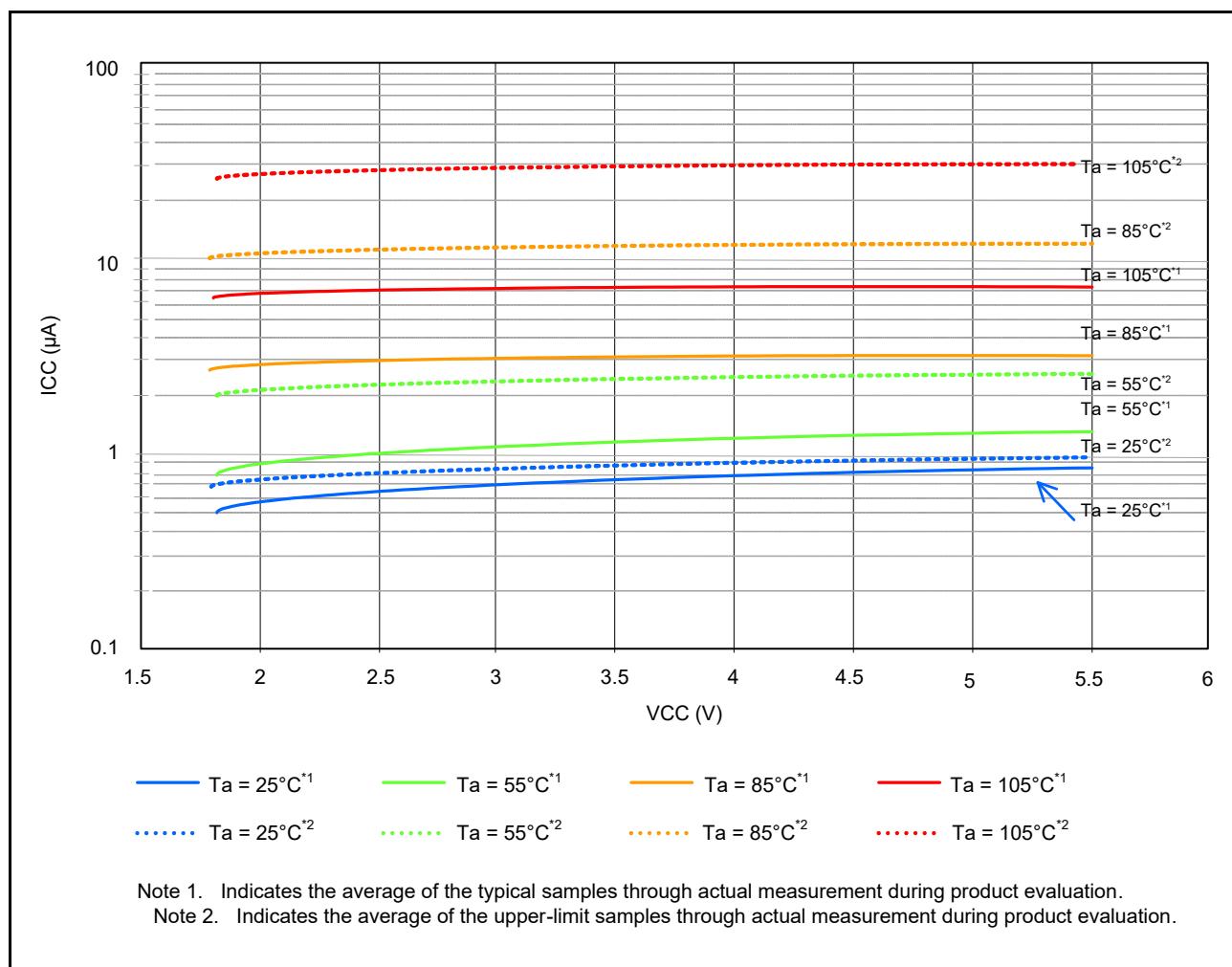
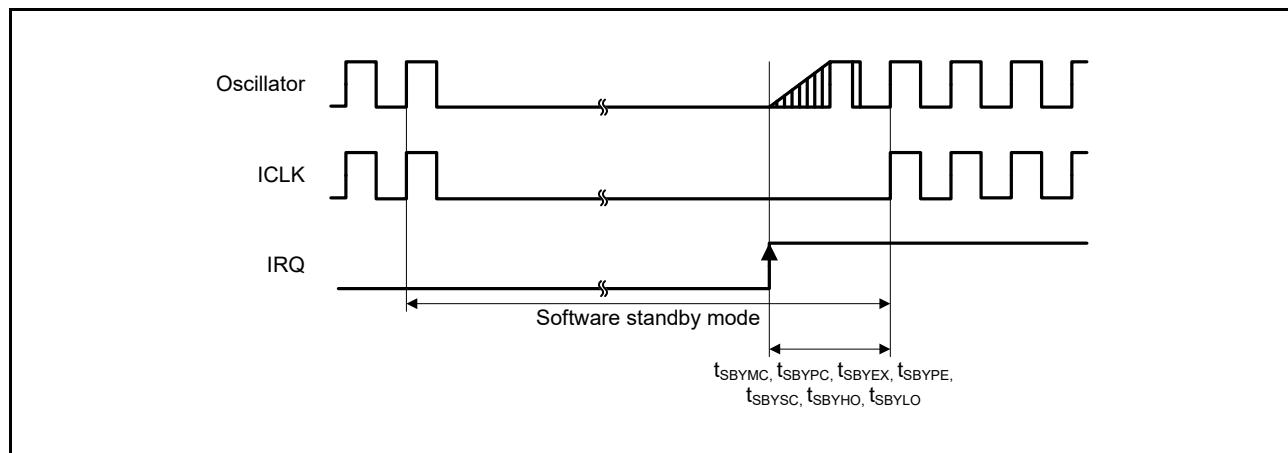
**Figure 5.4 Voltage Dependency in Software Standby Mode (Reference Data)**

Table 5.30 Timing of Recovery from Low Power Consumption Modes (3)Conditions: $1.8 \text{ V} \leq \text{VCC} = \text{VCC_USB} = \text{AVCC0} \leq 5.5 \text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VREFL0} = \text{VSS_USB} = 0 \text{ V}$, $T_a = -40 \text{ to } +105^\circ\text{C}$

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode ^{*1}	Low-speed mode	t_{SBYSC}	—	600	750	μs	Figure 5.34

Note 1. The sub-clock continues oscillating in software standby mode during low-speed mode.

**Figure 5.34 Software Standby Mode Recovery Timing****Table 5.31 Timing of Recovery from Low Power Consumption Modes (4)**Conditions: $1.8 \text{ V} \leq \text{VCC} = \text{VCC_USB} = \text{AVCC0} \leq 5.5 \text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VREFL0} = \text{VSS_USB} = 0 \text{ V}$, $T_a = -40 \text{ to } +105^\circ\text{C}$

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from deep sleep mode ^{*1}	High-speed mode ^{*2}	t_{DSLP}	—	2	3.5	μs	Figure 5.35
	Middle-speed mode ^{*3}	t_{DSLP}	—	3	4	μs	
	Low-speed mode ^{*4}	t_{DSLP}	—	400	500	μs	

Note 1. Oscillators continue oscillating in deep sleep mode.

Note 2. When the frequency of the system clock is 32 MHz.

Note 3. When the frequency of the system clock is 12 MHz.

Note 4. When the frequency of the system clock is 32 kHz.

5.14 E2 DataFlash Characteristics (Flash Memory for Data Storage)

Table 5.65 E2 DataFlash Characteristics (1)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N _{DPEC}	100000	1000000	—	Times	
Data hold time	After 10000 times of N _{DPEC}	t _{DDRP}	20*2, *3	—	—	Year	T _a = +85°C
	After 100000 times of N _{DPEC}		5*2, *3	—	—	Year	
	After 1000000 times of N _{DPEC}		—	1*2, *3	—	Year	T _a = +25°C

- Note 1. The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 100000), erasing can be performed n times for each block. For instance, when 1-byte programming is performed 1000 times for different addresses in a 1-Kbyte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).
- Note 2. Characteristic when the flash memory programmer is used and the self-programming library is provided from Renesas Electronics.
- Note 3. These results are obtained from reliability testing.

**Table 5.66 E2 DataFlash Characteristics (2)
: high-speed operating mode**

Conditions: 2.7 V ≤ VCC = VCC_{_USB} = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_{_USB} = 0 V

Temperature range for the programming/erasure operation: T_a = -40 to +105°C

Item	Symbol	FCLK = 1 MHz			FCLK = 32 MHz			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	t _{DP1}	—	95.0	797	—	40.8	376	μs
Erasure time	1 Kbyte	t _{DE1K}	—	19.5	498	—	6.2	230
	8 Kbyte		—	119.8	2556	—	12.9	368
Blank check time	1 byte	t _{DBC1}	—	—	55.00	—	—	16.1
	1 Kbyte	t _{DBC1K}	—	—	0.72	—	—	0.50
Erase operation forced stop time	t _{DSED}	—	—	16.0	—	—	10.7	μs
DataFlash STOP recovery time	t _{DSTOP}	5.0	—	—	5.0	—	—	μs

Note: The time until each operation of the flash memory is started after instructions are executed by software is not included.

Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note: The frequency accuracy of FCLK must be within ±3.5%.

**Table 5.67 E2 DataFlash Characteristics (3)
: middle-speed operating mode**

Conditions: 1.8 V ≤ VCC0 = VCC_{_USB} = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_{_USB} = 0 V

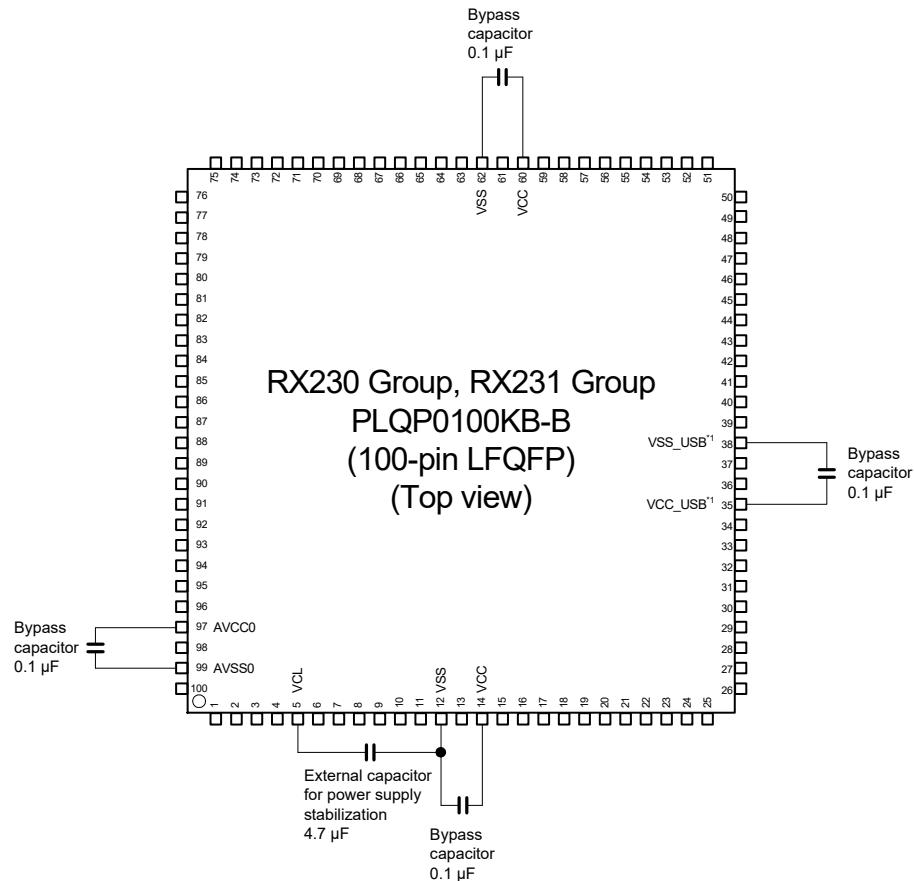
Temperature range for the programming/erasure operation: T_a = -40 to +85°C

Item	Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	t _{DP1}	—	135	1197	—	86.5	823	μs
Erasure time	1 Kbyte	t _{DE1K}	—	19.6	501	—	8.0	265
	8 Kbyte		—	120	2558	—	27.7	669
Blank check time	1 byte	t _{DBC1}	—	—	85.0	—	—	50.9
	1 Kbyte	t _{DBC1K}	—	—	0.72	—	—	1.45
Erase operation forced stop time	t _{DSED}	—	—	28.0	—	—	21.3	μs
DataFlash STOP recovery time	t _{DSTOP}	0.72	—	—	0.72	—	—	μs

Note: The time until each operation of the flash memory is started after instructions are executed by software is not included.

Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note: The frequency accuracy of FCLK must be within ±3.5%.



Note: Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic capacitor for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

Note 1. As the products of the RX230 group do not have VCC_USB or VSS_USB, a bypass capacitor is not required.

Figure 5.80 Connecting Capacitors (100 Pins)

Rev.	Date	Description		Classification
		Page	Summary	
1.20	Sep 28, 2018	95	Figure 5.12 VOH/VOL and IOH/IOL Temperature Characteristics at VCC = 5.5 V When Normal Output is Selected (Reference Data), changed	TN-RX*-A201A/E
		124	Table 5.44 Timing of On-Chip Peripheral Modules (7), added	TN-RX*-A197A/E
		131	Figure 5.64 SD Host Interface Input/Output Signal Timing, added	TN-RX*-A197A/E
		132	Table 5.45 USB Characteristics (USB0_DP and USB0_DM Pin Characteristics) conditions, changed	

All trademarks and registered trademarks are the property of their respective owners.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

- ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable.

When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

- ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.